Template for Projects Sources and Uses of Funds - Wafer Manufacturing, Semiconductor Materials, and Semiconductor Manufacturing Equipment Projects

Project 1 Sources and Uses template
Please refer to the Sources & Uses template instruction guide available for download in the pre-application section of the CHIPS incentives Portal and at this link: https://www.nist.gov/document/full-applicant-sources-and-uses-funds-instructions-semiconductor-materials-semiconductor
Please complete one template for each proposed project. Shared costs related to infrastructure improvements, workforce development, and other areas should be allocated across projects.

Add additional rows into the schedules as needed

Project 1 - Facility Name

Project 1 - Facility Description

		Percentage
Jses of Funds	Amount (USD)	eligible for ITC
. Capital Investment	0.00	
1.a. Land	0.00	
[Insert description]		
[Insert description]		
[Insert description]		
1.b. Construction	0.00	
[Insert description]		
1.c. Equipment	0.00	
[Insert description]		
[Insert description] [Insert description]		
[Insert description]		
[Insert description]		
1.d. Infrastructure Improvements	0.00	
[Insert description]		
1.e. Administrative Expenses directly attributable to facility construction	0.00	
[Insert description]		
1.f. Other	0.00	
[Insert description]		
. Operating losses and other cash outflows until project breaks even on a cash flow basis (Complete Sched		
3. Workforce Development Costs	0.00	
Equipment Costs		
Construction of Training Center		
Training and Education Costs		
Wrap-Around Support Costs		
Childcare Costs		
[Insert description]		
[Insert description]	1	1
[Insert description]		1
[Insert description]	1	1
[Insert description]		
. Other Uses of Funds	0.00	
[Insert description]		
[Insert description]	1	I

Schedule B: Project 1 - Funding Sources Schedule

Sources of Funds	Amount (US
1. Equity Funding	0
Sponsor Equity (Applicant and/or Corporate Parent)	
Third-Party Equity	
Other Equity Funding	
[Insert description]	
2. Debt Funding	
Intercompany Debt from Corporate Parent	
Third-Party Debt (e.g., Bonds or Loans)	
Unguaranteed portion of Third-Party Loans Guaranteed by CHIPS Program	
Other Debt Funding	
[Insert description]	
3. Government Support	
CHIPS Direct Funding CHIPS Loans	
Third-party Loans Guaranteed by CHIPS Program	
Investment Tax Credit (estimated)	
State and Local Government Grants	
State and Local Government Loans	
State and Local Tax Credits	
Other State and Local Government Incentives	
Other Federal grants, loans or guarantees	
[Insert description]	
I. Other Sources of Funds (examples provided below)	
Equipment Financing	
Sale Leaseback or Other Real Estate Financing	
Customer Funding	
[Insert description]	
Total Project Funding	

Schedule C: Project 1 - Schedule for Operating Cash Flows until Project breaks even on a Cash Flow basis

		Amount (USD)
Total sales until project breaks even on cash flow basis		0.0
2. Total operating expenses until project breaks even on a cash flow ba	sis	0.0
[Insert description]		
Operating Income / Losses (excluding other operating income)		0.0
3. Other operating income until project breaks even on a cash flow basi	s	0.0
[Insert description]		
Operating Income / Losses		0.0
4. Other cash flow items until project breaks even on a cash flow basis		0.0
[Insert description]		
Earnings Before Interest and Taxes		0.0
5. Total financing costs and taxes until project breaks even on a cash flo	w basis	0.0
Interest Paid to Service Debt		
Payments to Third-Party Partners		
Other Financing Costs		
[Insert description]		
[Insert description]		
[Insert description]		
Corporate Taxes		
Other Taxes		
[Insert description]		
[Insert description]		
[Insert description]		
Operating losses and other cash outflows until project breaks even on a	cash flow basis	0.00

Template for Projects Sources and Uses of Funds - Wafer Manufacturing, Semiconductor Materials, and Semiconductor Manufacturing Equipment Projects Full Application Stage

Project 2 Sources and Uses template
Please refer to the Sources & Uses template instruction guide available for download in the pre-application section of the CHIPS incentives Portal and at this link: https://www.nist.gov/document/full-applicant-sources-and-uses-funds-instructions-semiconductor-materials-semiconductor
Please complete one template for each proposed project. Shared costs related to infrastructure improvements, workforce development, and other areas should be allocated across projects.

Add additional rows into the schedules as needed

Project 2 - Facility Name

Project 2 - Facility Description

Schedule A: Project 2 - Uses Schedule

		Percentage
ses of Funds	Amount (USD)	
Capital Investment	0.00	
1.a. Land	0.00	
[Insert description]		
[Insert description]		
[Insert description]		
1.b. Construction	0.00	
[Insert description]		
1.c. Equipment	0.00	
[Insert description]		
[Insert description] [Insert description]		
[Insert description]		
[Insert description]		
1.d. Infrastructure Improvements	0.00	
[Insert description]		
1.e. Administrative Expenses directly attributable to facility construction	0.00	
[Insert description]		
[Insert description] 1.f. Other	0.00	
[Insert description]	0.00	
[Insert description]	0.00	
Operating losses and other cash outflows until project breaks even on a cash flow basis (Complete Sched	0.00	
Workforce Development Costs Equipment Costs	0.00	
Construction of Training Center		
Training and Education Costs		
Wrap-Around Support Costs		
Childcare Costs		
[Insert description]		
[Insert description] [Insert description]		
[Insert description]		
[Insert description]	0.00	
Other Uses of Funds	0.00	
[Insert description]		
[Insert description] [Insert description]		
	1	I

Schedule B: Project 2 - Funding Sources Schedule

Sources of Funds	Amount (US
L. Equity Funding	Amount (0)
Sponsor Equity (Applicant and/or Corporate Parent)	
Third-Party Equity	
Other Equity Funding	
[Insert description]	
[Insert description]	
[Insert description]	
2. Debt Funding	
Intercompany Debt from Corporate Parent	
Third-Party Debt (e.g., Bonds or Loans)	
Unguaranteed portion of Third-Party Loans Guaranteed by CHIPS Program	
Other Debt Funding	
[Insert description]	
3. Government Support	
CHIPS Direct Funding	
CHIPS Loans	
Third-party Loans Guaranteed by CHIPS Program	
Investment Tax Credit (estimated) State and Local Government Grants	
State and Local Government Grants State and Local Government Loans	
State and Local Tax Credits	
Other State and Local Government Incentives	
Other Federal grants, loans or guarantees	
[Insert description]	
4. Other Sources of Funds (examples provided below)	
Equipment Financing	
Sale Leaseback or Other Real Estate Financing	
Customer Funding	
[Insert description]	
[Insert description]	
[Insert description] Total Project Funding	

Schedule C: Project 1 - Schedule for Operating Cash Flows until Project breaks even on a Cash Flow basis

	Amount (USD)
1. Total sales until project breaks even on cash flow basis	0.00
Total operating expenses until project breaks even on a cash flow be	asis 0.00
[Insert description]	
Operating Income / Losses (excluding other operating income)	0.0
Other operating income until project breaks even on a cash flow ba	sis 0.00
[Insert description]	
Operating Income / Losses	0.0
Other cash flow items until project breaks even on a cash flow basis	0.0
[Insert description]	
Earnings Before Interest and Taxes	0.0
Total financing costs and taxes until project breaks even on a cash fl	ow basis 0.00
Interest Paid to Service Debt	
Payments to Third-Party Partners	
Other Financing Costs	
[Insert description]	
[Insert description]	
[Insert description]	
Corporate Taxes	
Other Taxes	
[Insert description]	
[Insert description]	
[Insert description]	
Operating losses and other cash outflows until project breaks even on	a cash flow basis 0.00

Template for Projects Sources and Uses of Funds - Wafer Manufacturing, Semiconductor Materials, and Semiconductor Manufacturing Equipment Projects

Summation across Projects Sources and Uses template
Please refer to the Sources & Uses template instruction guide for available for download in the full application section of the CHIPS Incentives Portal and at https://www.nist.gov/document/full-applicant-sources-and-uses-funds-instructions-semiconductor-materials-semiconductor
Each cell in the "Summation across Projects Sources and Uses" template should be a basic summation across each of the corresponding cells in every project template completed.

Add additional rows into the schedules as needed

Schedule A: Summation across projects - Uses Schedule

		Percentage
Jses of Funds		eligible for ITC
. Capital Investment	0.00	
1.a. Land	0.00	
[Insert description]		
[Insert description]		
[Insert description]	0.00	
1.b. Construction	0.00	
[Insert description]		
1.c. Equipment	0.00	
[Insert description]		
[Insert description]		
[Insert description] [Insert description]		
[Insert description]		
1.d. Infrastructure Improvements	0.00	
[Insert description]	0.00	
[Insert description]		
1.e. Administrative Expenses directly attributable to facility construction	0.00	
[Insert description]		
1.f. Other	0.00	
[Insert description]		
!. Operating losses and other cash outflows until project breaks even on a cash flow basis (Complete Schedu	0.00	
t. Operating losses and other cash outflows until project breaks even on a cash flow basis (complete scriedu I. Workforce Development Costs	0.00	
	0.00	
Equipment Costs		
Construction of Training Center		
Training and Education Costs		
Wrap-Around Support Costs		
Childcare Costs		
[Insert description]		
. Other Uses of Funds	0.00	
[Insert description]		
[Insert description]		
[Insert description]	1	
i. Total Project Costs	0.00	

Schedule C: Project 1 - Schedule for Operating Cash Flows until Project breaks even on a Cash Flow basis

	Amount (USD)
1. Total sales until project breaks even on cash flow basis	0.00
2. Total operating expenses until project breaks even on a cash flow basis	0.00
[Insert description]	
Operating Income / Losses (excluding other operating income)	0.00
3. Other operating income until project breaks even on a cash flow basis	0.00
[Insert description]	
Operating Income / Losses	0.00
4. Other cash flow items until project breaks even on a cash flow basis	0.00
[Insert description]	
Earnings Before Interest and Taxes	0.00
5. Total financing costs and taxes until project breaks even on a cash flow basis	0.00
Interest Paid to Service Debt	
Payments to Third-Party Partners	
Other Financing Costs	
[Insert description]	
[Insert description]	
[Insert description]	
Corporate Taxes	
Other Taxes	
[Insert description]	
[Insert description]	
[Insert description]	
Operating losses and other cash outflows until project breaks even on a cash flow basis	0.00

Schedule B: Summation across projects - Funding Sources Schedule

Commence of French	A
ources of Funds	Amount (USD)
L. Equity Funding	0.0
Sponsor Equity (Applicant and/or Corporate Parent)	
Third-Party Equity	
Other Equity Funding	
[Insert description]	
2. Debt Funding	0.0
Intercompany Debt from Corporate Parent	
Third-Party Debt (e.g., Bonds or Loans)	
Unguaranteed portion of Third-Party Loans Guaranteed by CHIPS Program	
Other Debt Funding	
[Insert description]	
3. Government Support	0.0
CHIPS Direct Funding	
CHIPS Loans	
Third-party Loans Guaranteed by CHIPS Program Investment Tax Credit (estimated)	
State and Local Government Grants	
State and Local Government Loans	
State and Local Tax Credits	
Other State and Local Government Incentives	
Other Federal grants, loans or guarantees	
[Insert description]	
4. Other Sources of Funds (examples provided below)	0.0
Equipment Financing	
Sale Leaseback or Other Real Estate Financing	
Customer Funding	
[Insert description]	
[insert description] Total Project Funding	0.0